



10-14-04

Express Mail No. EV 346 811 856 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Takeshi AKATSU

Confirmation No.: 2732

Application No.: 10/827,437

Group Art Unit: 1765

Filing Date: April 20, 2004

Examiner:

For: METHOD OF FABRICATION OF A
SUBSTRATE FOR AN EPITAXIAL GROWTH

Attorney Docket No.: 4717-13000

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed are copies of (6) references for the Examiner's review and consideration. These references was cited in the European Search Report and a copy is enclosed.

These references are listed on the enclosed Form PTO-1449. It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee is believed to be due for the filing of this statement as it is being submitted prior to an initial office action for this application. Should any fees be required, however, please charge such fees to Winston & Strawn LLP Deposit Account No. 50-1814.

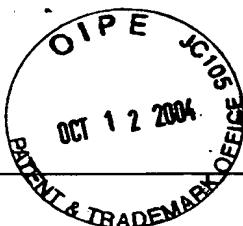
Respectfully submitted,

Date: 10/12/04


Allan A. Fanucci (Reg. No. 30,256)

WINSTON & STRAWN LLP
CUSTOMER NO. 28765
(212) 294-3311

Enclosure



LIST OF REFERENCES CITED BY APPLICANT <i>(Use several sheets if necessary)</i>					ATTY. DOCKET NO.:	APPLICATION NO.:		
					4717-13000	10/827,437		
					APPLICANT:			
					Takeshi AKATSU			
FILING DATE: April 20, 2004					GROUP: 1765			
U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME		CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	6,524,935 B1	2/2003	Canaperi et al.		438	478	
	AB							
	AC							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AD	EP 1 258 544 A1	11/2002	Europe			X	
	AE	WO 03/009366 A1	1/2003	PCT			X	
	AF							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AG	L. Huang et al., XP001116664 "Electron And Hole Mobility Enhancement In Strained SOI By Wafer Bonding", IEEE Transactions On Electron Devices, Vol. 49, No. 9, pp. 1566-1567 (2002).						
	AH	L. Huang et al., XP001020601, "Sige-On-Insulator Prepared By Wafer Bonding And Layer Transfer For High-Performance Field-Effect Transistor", Applied Physics Letters, American Institute Of Physics, Vol. 78, No. 9, pp 1267-1269, (2001).						
	AI	C. Maleville et al., XP-001003462, "Multiple SOI Layers By Multiple Smart-Cut Transfers", 2000 IEEE International SOI Conference, pp. 134-135, (2000).						
	AJ							
	AK							
EXAMINER					DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								